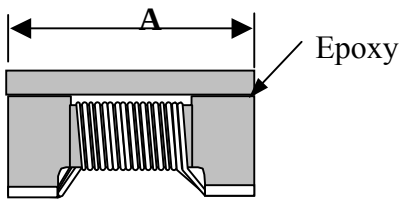
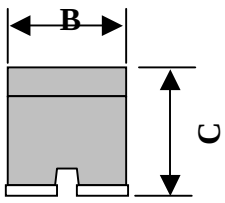
Common Mode Filter

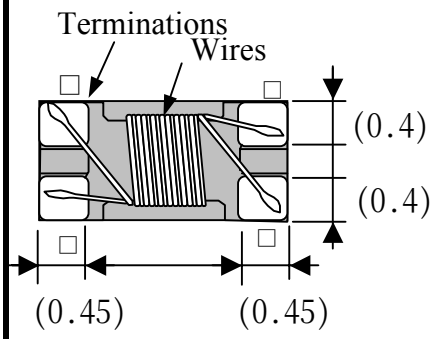
AXIS POWER 經軸電子

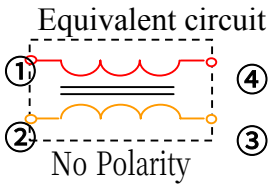
BCCUB-T4P-2012 SERIES

SHAPES & DIMENSIONS









A : 2.0 ± 0.2
B : 1.2 ± 0.2
C : 1.2 ± 0.2

ELECTRICAL CHARACTERISTICS

IMPEDANCE (Ω)	REFERENCE PAGE.2
DCR	
RATED CURRENT	
RATED VOLTAGE	
WITHSTAND VOLTAGE	

ORDERING CODE :

BCCUB – T4P – 2012 – □□□ T

(1) (2) (3) (4) (5)

(1) Product Code
(2) Number of Pins
(3) Size Code
(4) Impedance Value Code
(5) Taping

TEST FREQUENCY

100 MHz

TEST EQUIPMENT

IMPEDANCE TEST BY E4991A
DCR TEST BY CH-16502

Common Mode Filter

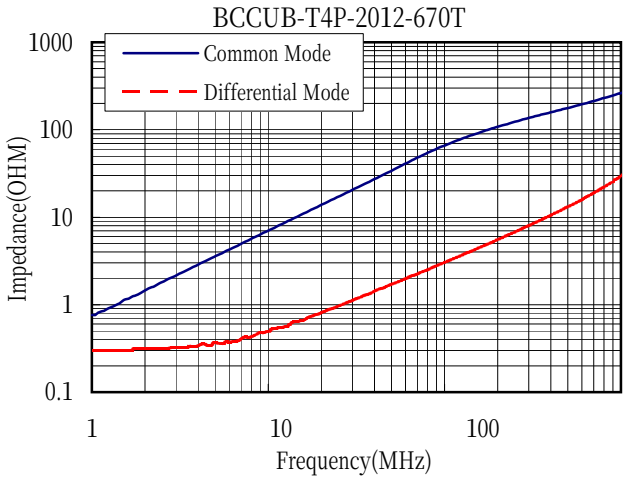
AXIS POWER 經軸電子

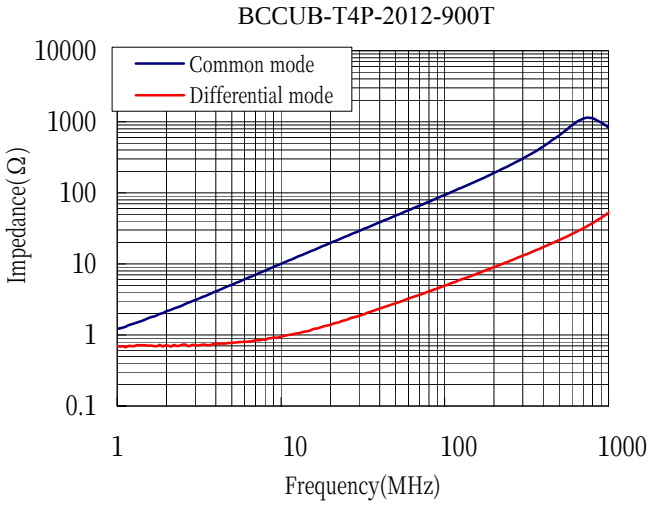
BCCUB-T4P-2012 SERIES

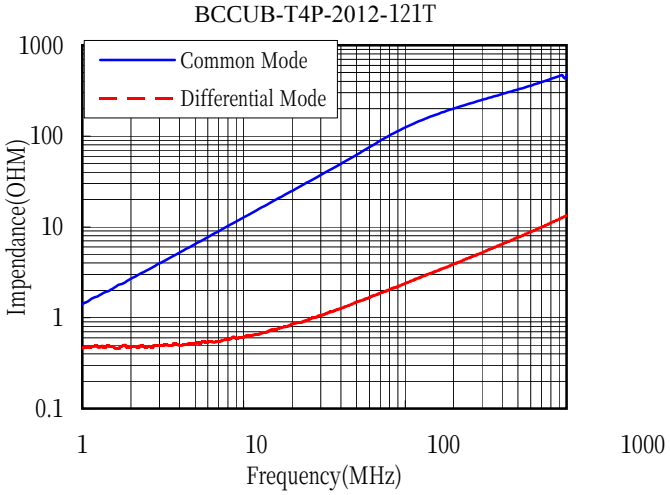
Electrical Characterisitics
Electrical Spec.

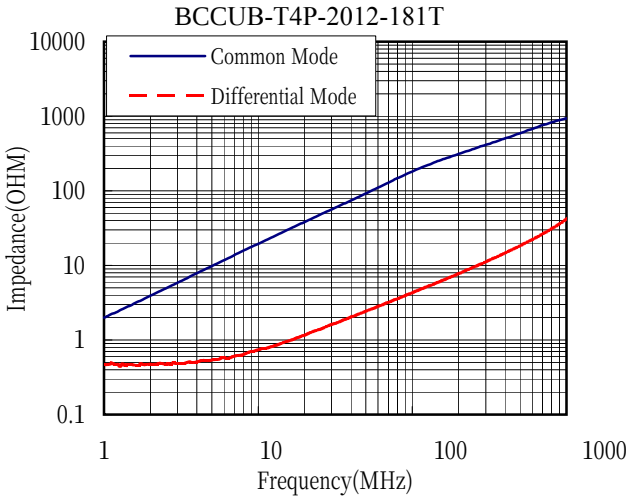
Part Number	Common-Mode Impedance Z(Ω) at 100MHz	DC Resistance Rdc(Ω) Max.	Rated Current Idc(mA) Max.	Rated Voltage Vdc(V)	Insulation Resistance (MΩ)Min.
BCCUB-T4P-2012-670T	67 ±25%	0.25	400	50	10
BCCUB-T4P-2012-900T	90 ±25%	0.35	330	50	10
BCCUB-T4P-2012-121T	120±25	0.30	370	50	10
BCCUB-T4P-2012-181T	180±25%	0.35	330	50	10
BCCUB-T4P-2012-261T	260±25%	0.40	300	50	10
BCCUB-T4P-2012-371T	370±25%	0.40	280	50	10

Characteristics(Reference)









Common Mode Filter

AXIS POWER 經軸電子

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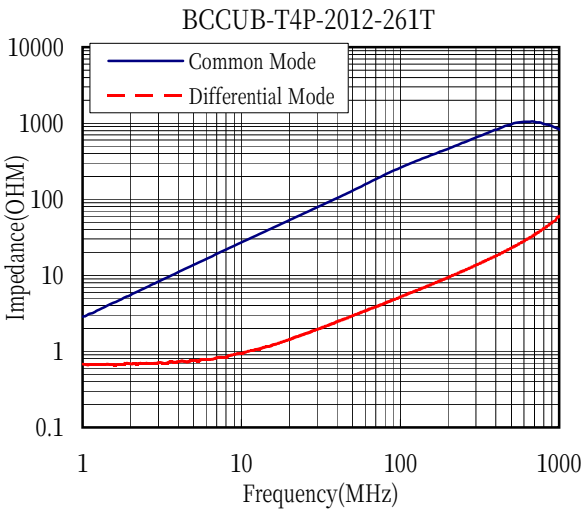
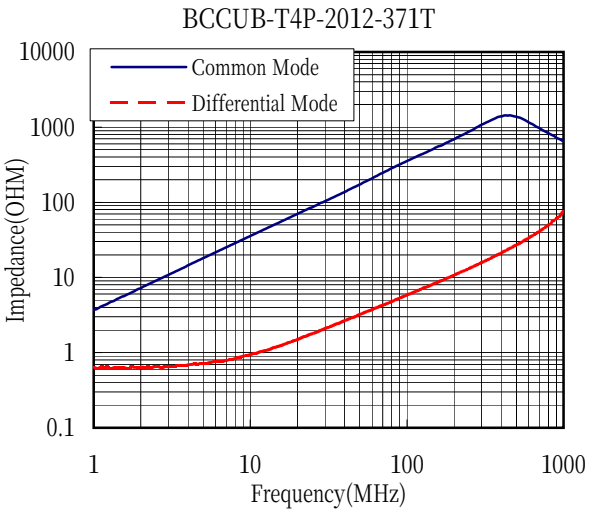


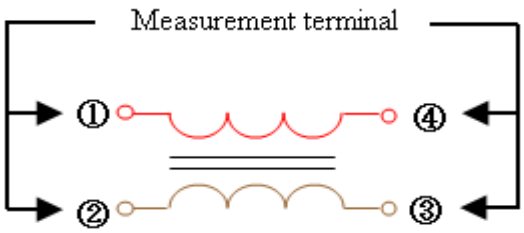


BCCUB-T4P-2012 SERIES

Test Equipment

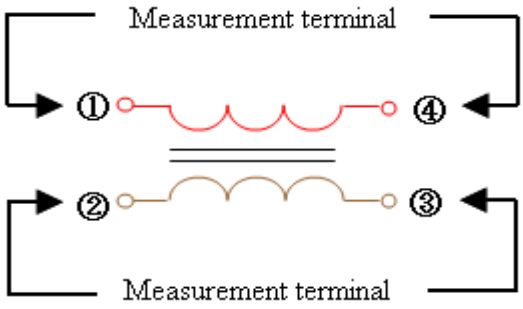
1. Impedance

Measured by using Agilent E4991A RF Impedance Analyzer.



2. DC Resistance

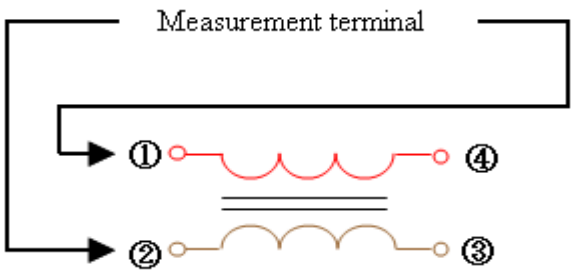
Measured by using Chroma 16



3. Insulation Resistance

Measured by using Chroma 19073

Measurement voltage : 50v .



Common Mode Filter

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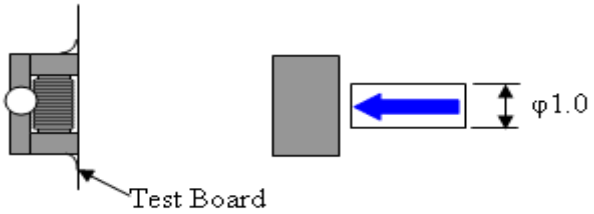
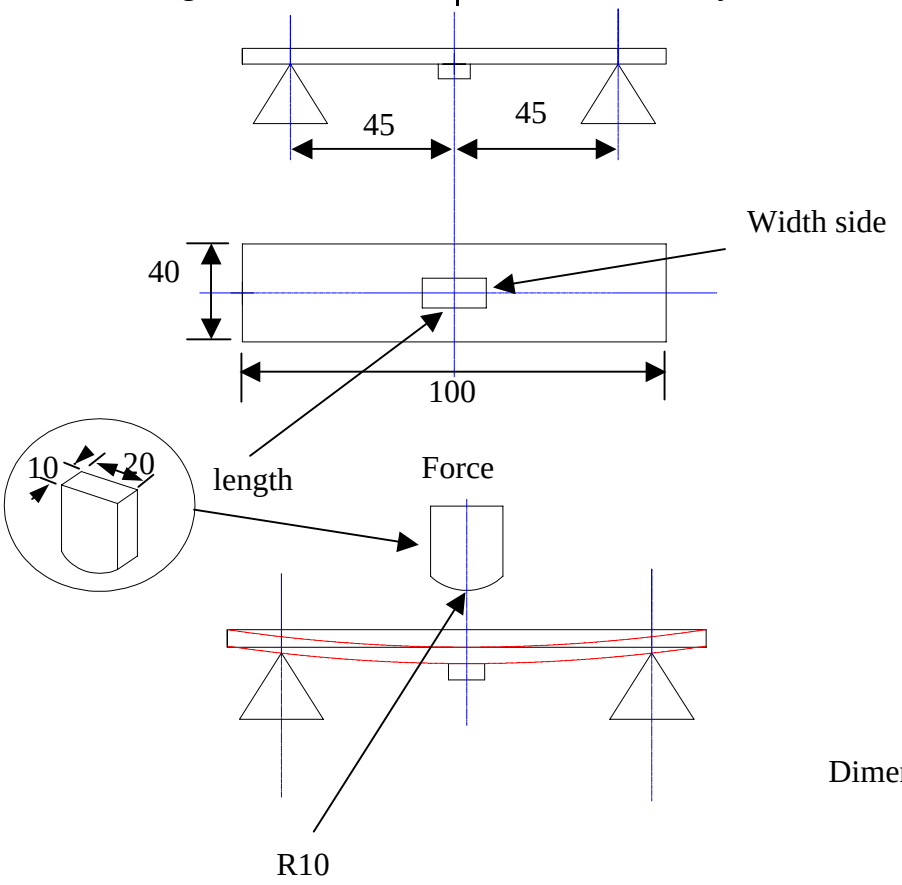
Operating temperature : -25 to +85℃		Storage temp and humidity : 20~25℃ ,60%RH max.
Item	Specifications	Test conditions
Solder ability	It can be connected on the Recommendation soldering condition.	Apply cream solder to the test circuit board . It is mounted on the recommendation soldering condition. Dip pads in flux and dip in solder pot(96.5 Sn/3.5 Ag solder) at 255°C ±5°C.
Terminal strength	The terminal electrode and the ferrite must not be damaged.	Solder a chip to test substrate , and then laterally apply a load 0.5Kg in the arrow direction. 
Strength on pc board bending	The terminal electrode and the ferrite must not be damaged.	Soldering a chip to a test substrate , bend the substrate by 2mm and then return.  Dimensions in mm Test board : Glass base epoxy multiplayer board pc board pattern. PC board pattern : Recommended PC board pattern.

Common Mode Filter

AXIS POWER 經軸電子

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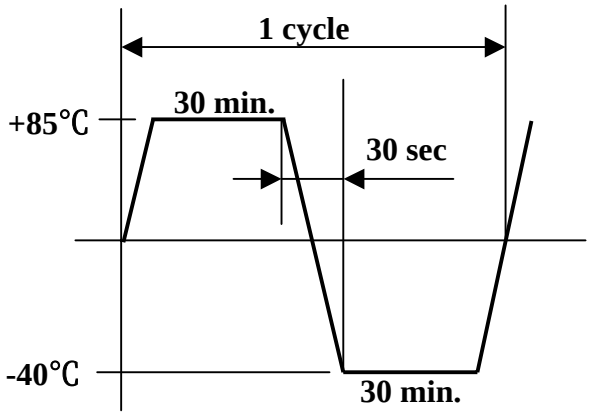
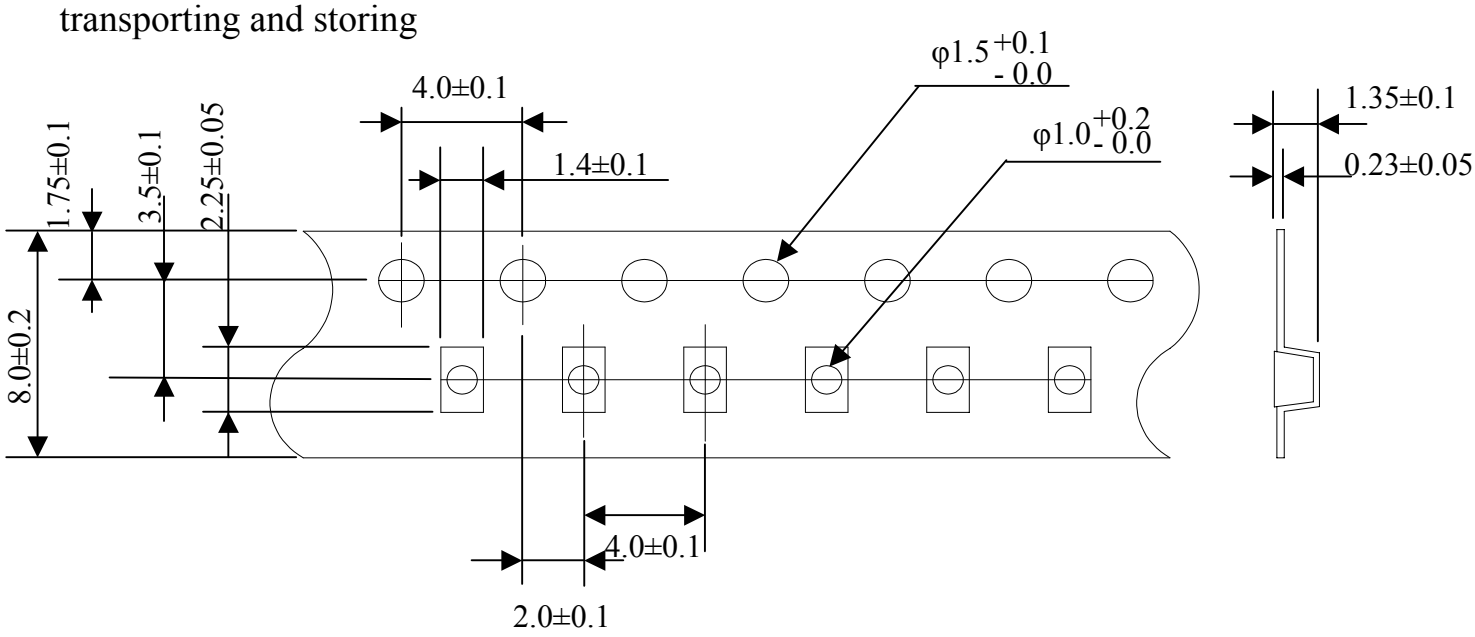
Item	Specifications	Test conditions
High temperature resistance	Appearance : Ferrite shall not be damaged. initial value. insulation resistance: >10(MΩ) DC resistance : standard value inside.	Temperature : +85±2℃ Applied voltage : Rated voltage Applied current : Rated current Testing time : 50±12 hours Measurement : After placing for 24 hours min.
Humidity resistance		Temperature : +85±2℃ Humidity : 90 to 95%RH Applied current : Rated current Applied voltage : Rated voltage Testing time : 500±12 hours Measurement : After placing for 24 hours min.
Thermal shock		Temperature : -25℃,+85℃ kept stabilized for 30 minutes each. Cycle : 100 cycle Measurement : After placing for 24 hours min. 
Low temperature resistance		Temperature : -25±2℃ Testing time : 48±12 hours Measurement : After placing for 24 hours min.
Vibration	Appearance : Ferrite shall not be damaged.	Frequency : 10 to 50 Hz Amplitude : 1.52 mm Dimension and times : X ,Y and Z directions for 2 hours each.

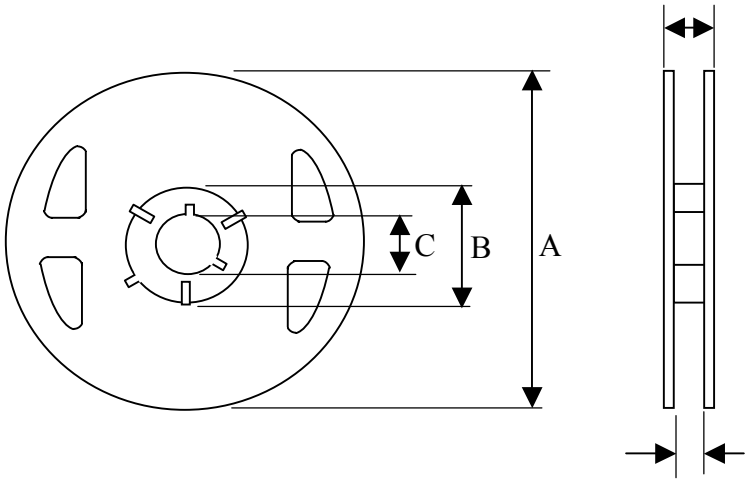
BCCUB-T4P-2012 SERIES

Packaging

The packaging must be done not to receive any damage during transporting and storing



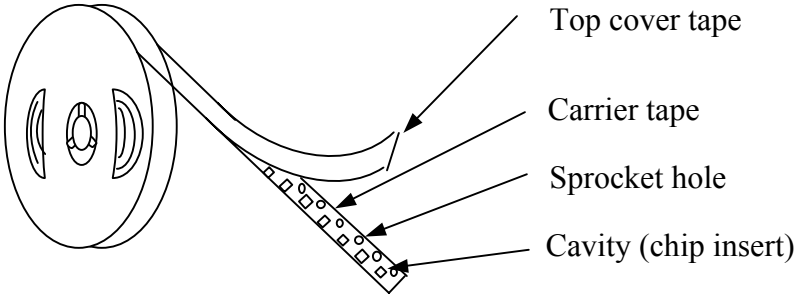
Reel dimensions



Dimension in mm

Symbol	T
φA	180+0,-3
φB	60+1,-0
φC	13±0.2
D	2.2±0.5
W	9.0±0.3
t	1.2
R	1

Tapping figure



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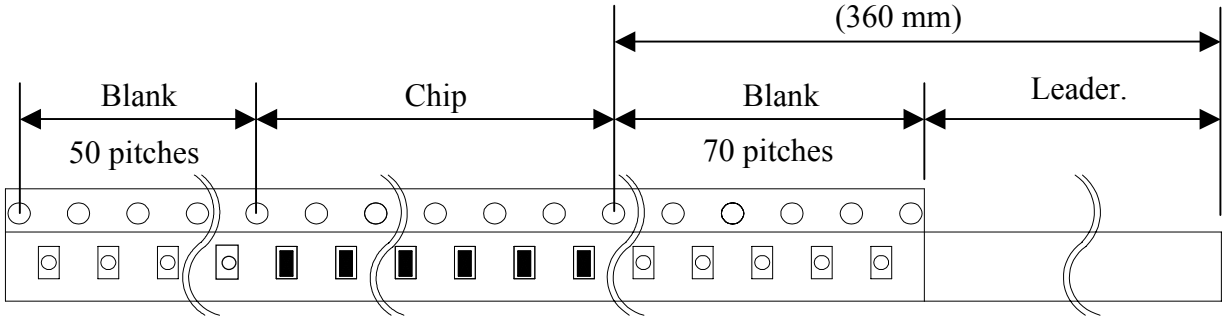
Packaging Form

There shall not continuation more than two vacancies of the product.

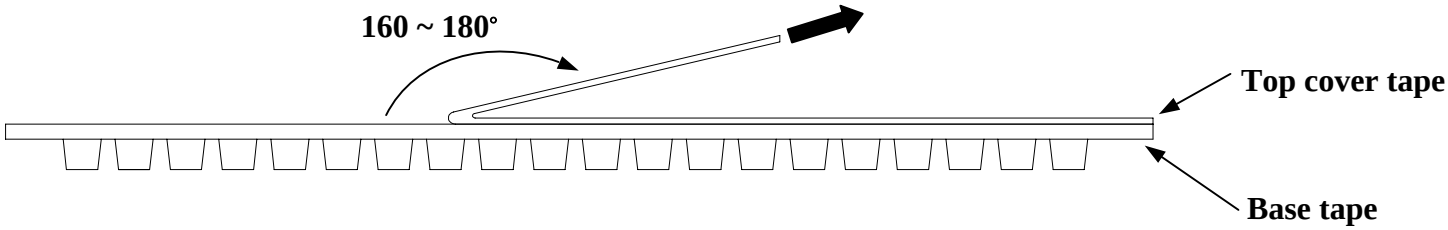


Material of carrier tape : Polyst
Material of cover tape : Polyest

Cover Tape Peel Strength

The force for tearing off cover tape is 0.05~0.69(N) in the arrow direction at the following conditions:

Temperature : 5 ~ 35℃
Humidity : 45 ~ 85%
Atmospheric pressure : 860 ~ 1060 hpa



Packing Quantity

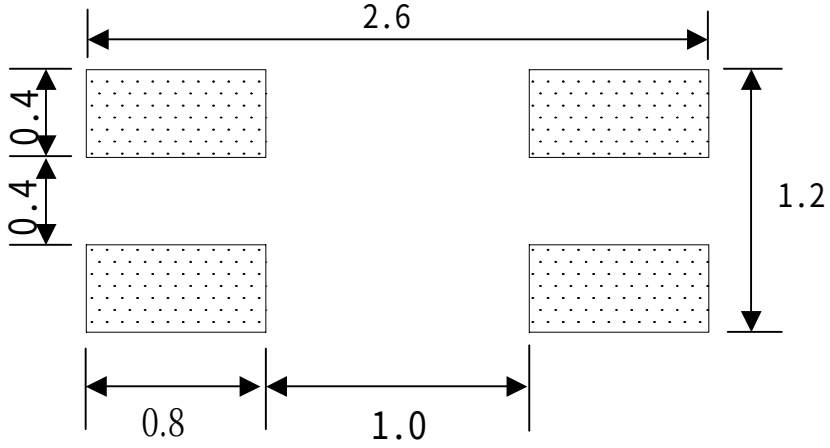
φ180 mm reel T type : 3000 pcs./reel

Recommended Soldering Conditions

(Please use this product by reflow soldering)

***Recommended Footprint**

Termination Number : Please refer to the equivalent circuit in chapter 3.



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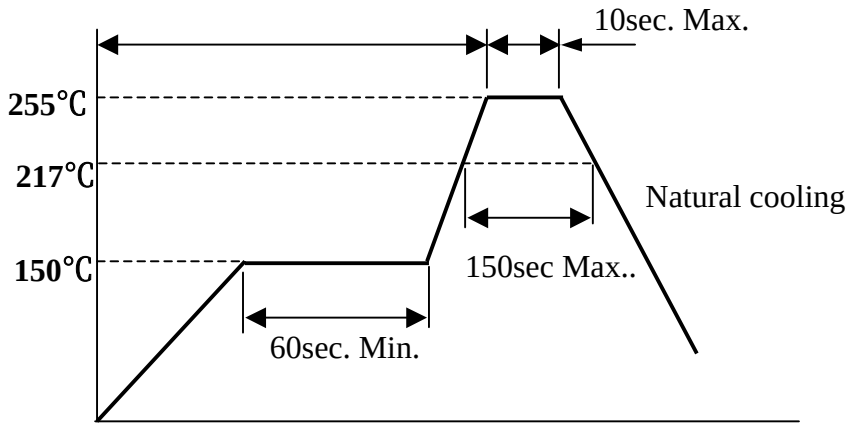
***Recommended Reflow Pattern**

Reflow : until two times



*** Iron Soldering**

Use a solder iron of less than 30W when soldering ,do not allow the soldering iron tip directly touch the ferrite body outside of terminal electrode.

4 seconds max. at 260℃.

Attention in Case of Using

In case of using product ,please avoid following matters:

Splashing water or salt water

Dew condenses

Toxic gas (Hydrogen sulfide, Sulfurous acid ,Chlorine, Ammonia)

Vibrations or shocks which exceed the specified cond

Please be careful for the stress to this product by board flex after the mounting.

Others

*Operating temperature range : -25~＋85℃

*Storage condition : Temperature 20~25℃ , Relative Humidity 40% ~ 60%